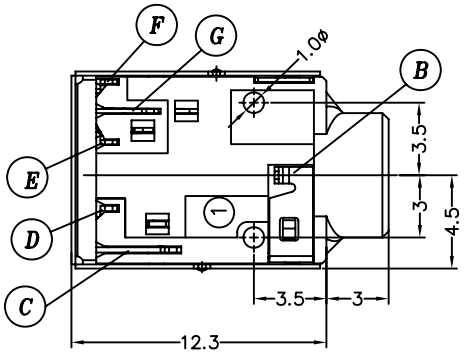
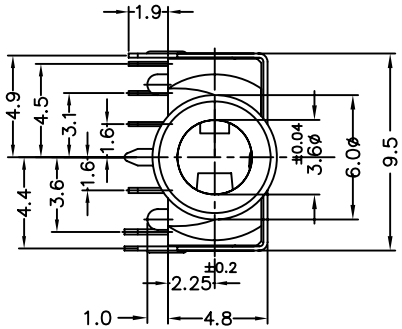
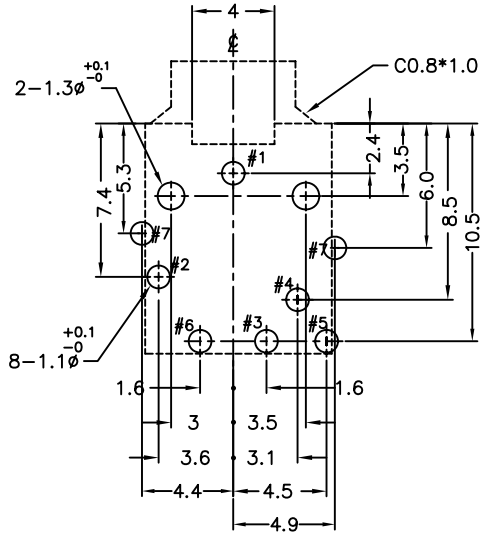
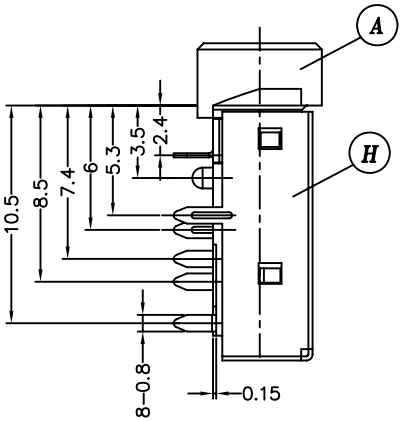
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR :T091124-3A	HX	2009.12.25









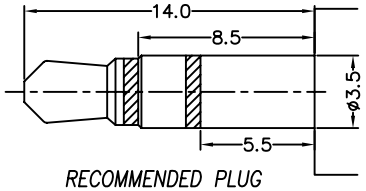
SPECIFICATIONS:

1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
2. CONTACT RESISTANCE: 30mΩ MAX.
3. INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE:0.4 - 3Kg.
7. WITHDRAWAL FORCE:0.3 - 2Kg.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE:50MΩ MIN.
10. MARKING: MARK" " ON TOP OF CONNECTOR.
11. PACKAGING : TAPE & REEL.
12. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
13. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
14. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING
15. FOR LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 1.5 μm MIN.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120u" Sn ON SOLDER TAIL. GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni.
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA OVER 50u" Ni.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	ALL OVER GOLD FLASH ALL OVER 50u" Ni .
B	EARTH	1	COPPER ALLOY 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK COLOR

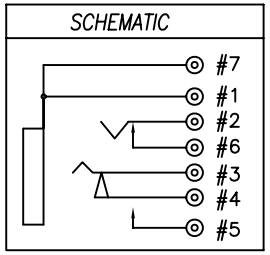
RECOMMENDED PCB LAYOUT (TOP VIEW)

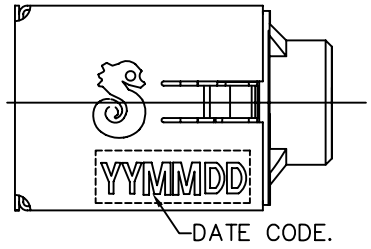
(TOLERANCE: ±0.05)



RECOMMENDED PLUG

3-POLE





UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: ANGLES:
X. :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2
X.XXX :±0.1

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK		
DWN	HX 2009.12.25	PART NO. 2SJ-S351-061	
CHKD	BOYE 2010.1.5	SCALE:4/1	UNIT: mm
APVD	MAX 2010.1.5	SIZE: A3	SHEET:1 OF 1 REV:A

CUSTOMER COPY

文件編號: RD-06-043-A